



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-22
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7ZDP*U23P125	A	SH1A	2014-07-22
Amount	UoM	Unit type	ST ECOPACK Grade	
320.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.5X6.1X2.3	2	gull wing	
Comment	Package: TO 252 DPAK; MD valid for STPS15H100CB; STPS15H100CB-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7ZDP*U23P125					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.317	mg	supplier	die	Silicon (Si)	7440-21-3		5.902	mg	934304	18444
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.244	mg	38626	763
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	792	16
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	1425	28
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.027	mg	4274	84
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.036	mg	5699	113
die (s)				supplier	passivation	Esterified polyamid	63428-83-1		0.038	mg	6016	119
die (s)				supplier	passivation	Tetraethylene glycol dimethacrylate	109-17-1		0.004	mg	633	13
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	475	9
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1425	28
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.04	mg	6332	125
Leadframe	Copper & its alloys	154.666	mg	supplier	alloy	Copper (Cu)	7440-50-8		154.366	mg	998060	482394
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.155	mg	1002	484
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.046	mg	297	144
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	595	288
Leadframe				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	45	22
Soft solder	Other Organic Materials	4.668	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.458	mg	955013	13931
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.117	mg	25064	366
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.093	mg	19923	291
Bonding wire	Other inorganic materials	0.692	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.692	mg	1000000	2163
encapsulation	Other Organic Materials	152.612	mg	supplier	mold compound	Silica, vitreous	60676-86-0		122.09	mg	800003	381531
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.683	mg	70001	33384
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		6.104	mg	39997	19075
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		9.157	mg	60002	28616
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		1.831	mg	11998	5722
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		2.289	mg	14999	7153
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.458	mg	3001	1431
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266